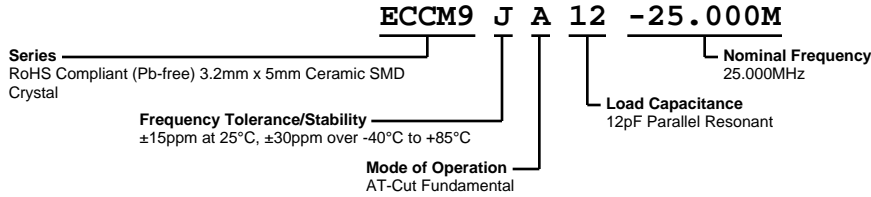


# ECCM9JA12-25.000M



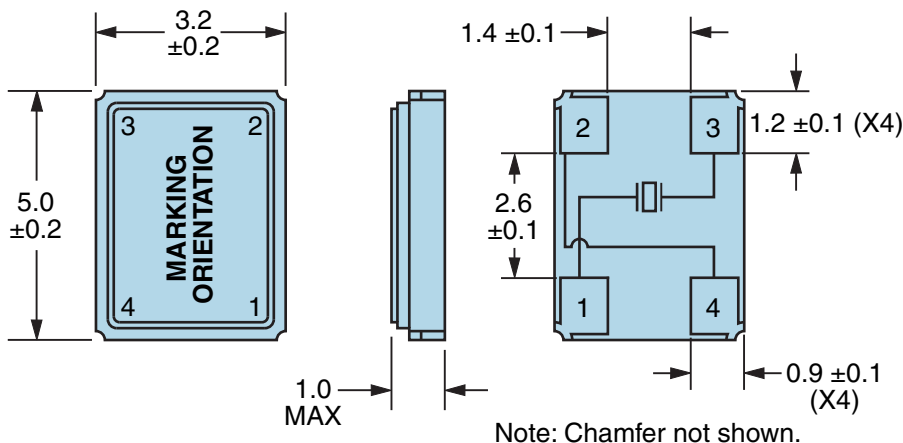
## ELECTRICAL SPECIFICATIONS

Nominal Frequency	25.000MHz
Frequency Tolerance/Stability	$\pm 15\text{ppm}$ at 25°C, $\pm 30\text{ppm}$ over -40°C to +85°C
Aging at 25°C	$\pm 3\text{ppm/Year}$ Maximum
Load Capacitance	12pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	50 Ohms Maximum
Mode of Operation	AT-Cut Fundamental
Drive Level	100μWatts Maximum, 10μWatts Correlation
Crystal Cut	AT-Cut
Spurious Response	>3dB from Fo to Fo+5000ppm
Storage Temperature Range	-40°C to +125°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	<b>E25.00</b> E=Ecliptek
2	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier

# ECCM9JA12-25.000M

## Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

**$T_s$  MAX to  $T_L$  (Ramp-up Rate)** 3°C/second Maximum

#### Preheat

- Temperature Minimum ( $T_s$  MIN) 150°C
- Temperature Typical ( $T_s$  TYP) 175°C
- Temperature Maximum ( $T_s$  MAX) 200°C
- Time ( $t_s$  MIN) 60 - 180 Seconds

**Ramp-up Rate ( $T_L$  to  $T_p$ )** 3°C/second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 217°C
- Time ( $t_L$ ) 60 - 150 Seconds

**Peak Temperature ( $T_p$ )** 260°C Maximum for 10 Seconds Maximum

**Target Peak Temperature ( $T_p$  Target)** 250°C +0/-5°C

**Time within 5°C of actual peak ( $t_p$ )** 20 - 40 seconds

**Ramp-down Rate** 6°C/second Maximum

**Time 25°C to Peak Temperature (t)** 8 minutes Maximum

**Moisture Sensitivity Level** Level 1

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

<b>T<sub>s</sub> MAX to T<sub>L</sub> (Ramp-up Rate)</b>	5°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum (T <sub>s</sub> MIN)	N/A
- Temperature Typical (T <sub>s</sub> TYP)	150°C
- Temperature Maximum (T <sub>s</sub> MAX)	N/A
- Time (t <sub>s</sub> MIN)	60 - 120 Seconds
<b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>	5°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature (T <sub>L</sub> )	150°C
- Time (t <sub>L</sub> )	200 Seconds Maximum
<b>Peak Temperature (T<sub>P</sub>)</b>	240°C Maximum
<b>Target Peak Temperature (T<sub>P</sub> Target)</b>	240°C Maximum 1 Time / 230°C Maximum 2 Times
<b>Time within 5°C of actual peak (t<sub>p</sub>)</b>	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.